

INTERNATIONAL STANDARD



**Printed electronics –
Part 202-5: Materials – Conductive ink – Mechanical bending test of a printed
conductive layer on an insulating substrate**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED ELECTRONICS –

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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INTRODUCTION

The printing process is a highly promising technology for the fabrication of flexible devices. In particular, a printed conductive layer on an insulating substrate will be widely employed as an electrode or as an interconnect for flexible devices. It will be dealt with and commercialized as a type of composite material in which the conductive layer is formed on the substrate as a conductor.

For a conductive film, the electrical property under mechanical deformation is very important because it is highly sensitive to mechanical stress and degrades well before the mechanical fracture. Therefore, a method for evaluating the conductivity of film materials provided by suppliers, sometimes including an *in situ* measurement system, is required in the industry as these are the basic materials which will be used in printed devices. Although some bending tests already exist, it is necessary to consider the unique characteristics of the printed films that are fabricated on a polymer substrate, which is weak under high temperature. These films are operated under severe mechanical deformations, unlike the conventional Si- or glass-based conductive films.

In this document, a mechanical bending test is described to evaluate the electrical property of a printed conductive layer on a substrate under repeated mechanical deformations. This sliding plate test method can be available for practical application in the industry by enabling the long-term reliability testing of printed film.